

**Integrated chip package structure using organic substrate and method of
manufacturing the same**

Appl. No. : 10/055,499 Confirmation No. 7456
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Filed : January 22, 2002
TC/A.U. : 2891
Examiner : THAI, LUAN C
Docket No. : MEGP0012USA
Customer No. : 27765

Commissioner for Patents
P.O. Box 1450
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AMENDMENT AFTER NOTICE OF ALLOWANCE

5 Sir:

Please enter the following amendment to the above-identified patent application and consider the remarks as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

10 **Remarks/Arguments** begin on page 13 of this paper.